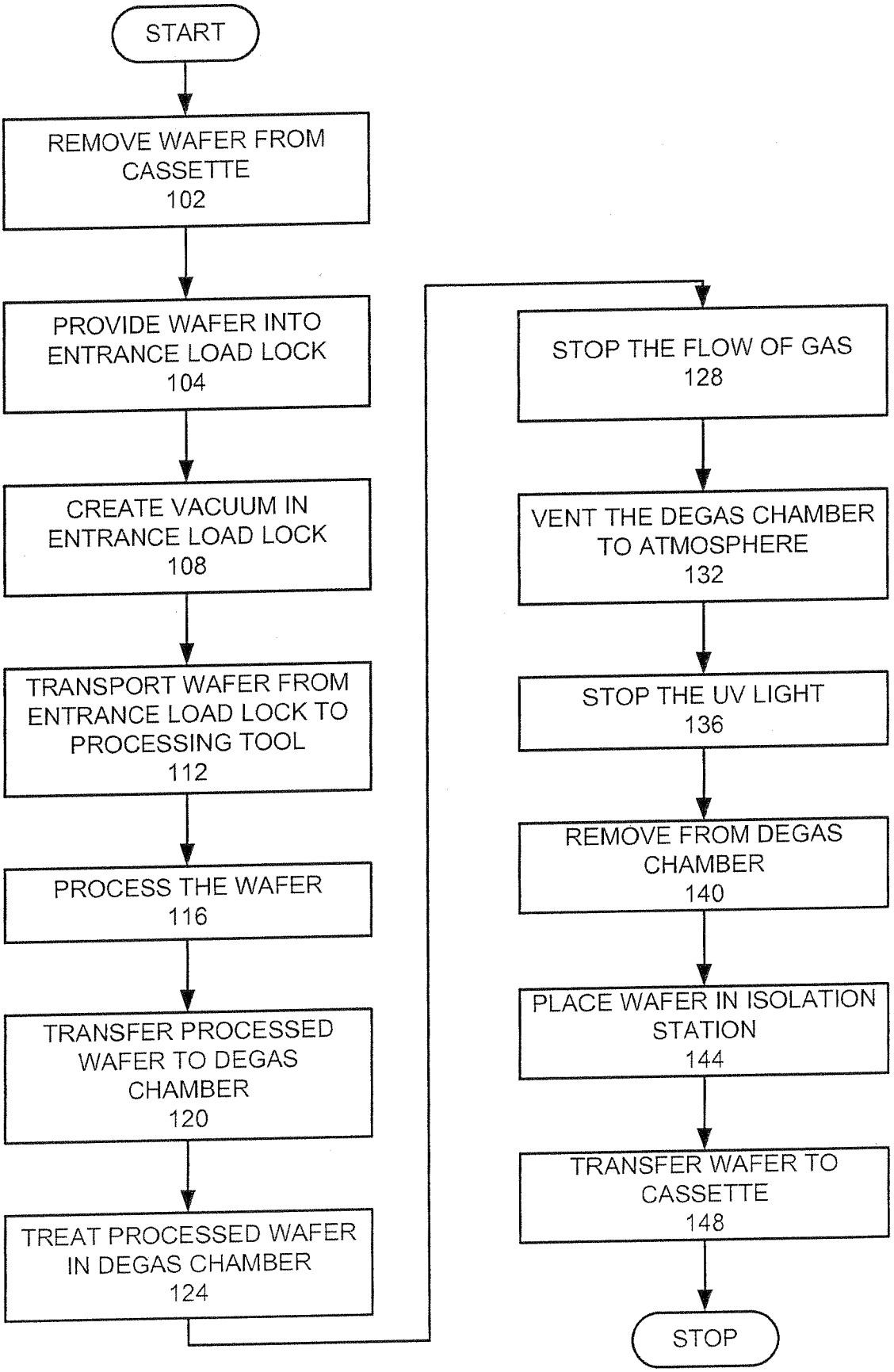

START
REMOVE WAFER FROM CASSETTE 102
PROVIDE WAFER INTO ENTRANCE LOAD LOCK 104
CREATE VACUUM IN ENTRANCE LOAD LOCK 108
TRANSPORT WAFER FROM ENTRANCE LOAD LOCK TO PROCESSING TOOL 112
PROCESS THE WAFER 116
TRANSFER PROCESSED WAFER TO DEGAS CHAMBER 120
TREAT PROCESSED WAFER IN DEGAS CHAMBER 124
STOP THE FLOW OF GAS 128
VENT THE DEGAS CHAMBER TO ATMOSPHERE 132
STOP THE UV LIGHT 136
REMOVE FROM DEGAS CHAMBER 140
PLACE WAFER IN ISOLATION STATION 144
TRANSFER WAFER TO CASSETTE 148
STOP

FIG. 1

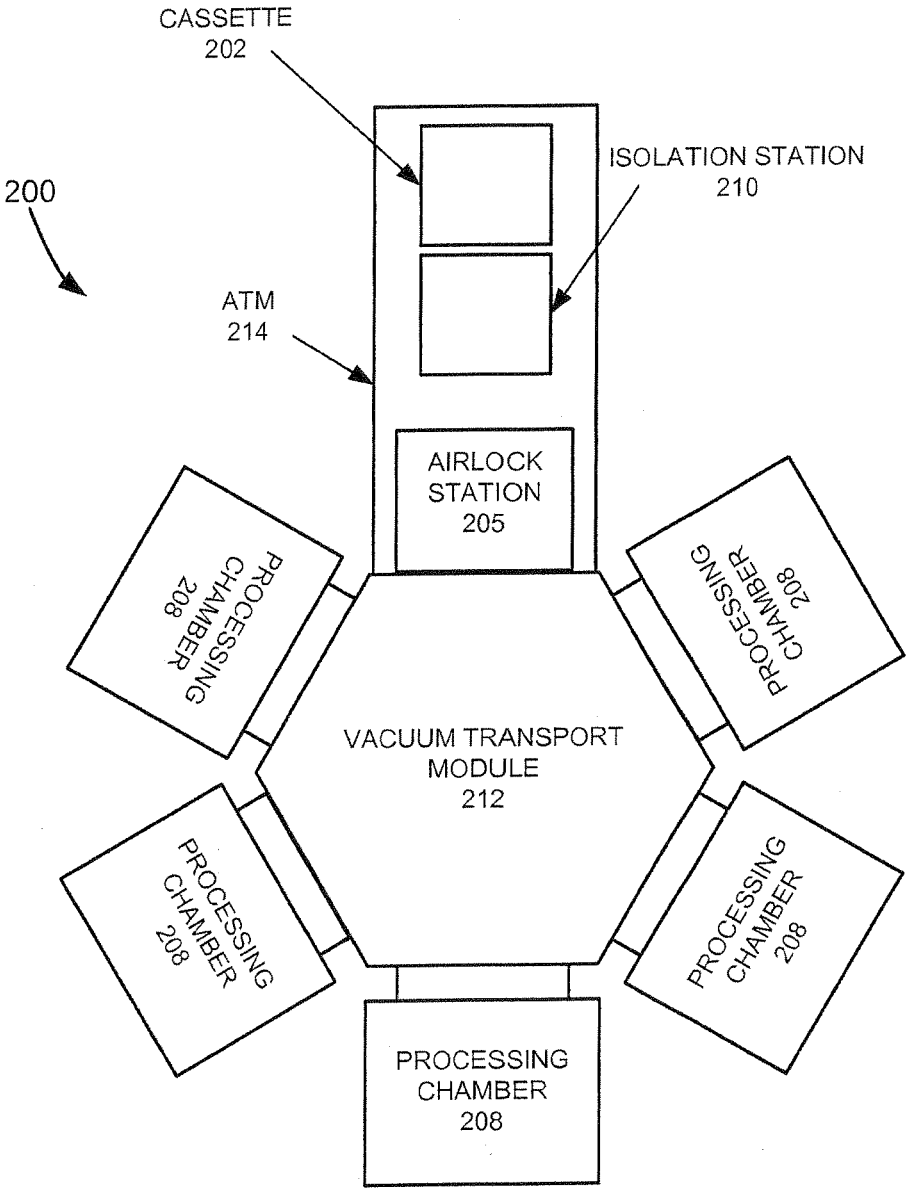

CASSETTE
202
200
ISOLATION STATION
210
ATM
214
AIRLOCK
STATION
205
PROCESSING
CHAMBER
208
PROCESSING
CHAMBER
208
VACUUM TRANSPORT
MODULE
212
PROCESSING
CHAMBER
208
PROCESSING
CHAMBER
208
PROCESSING
CHAMBER
208

FIG. 2

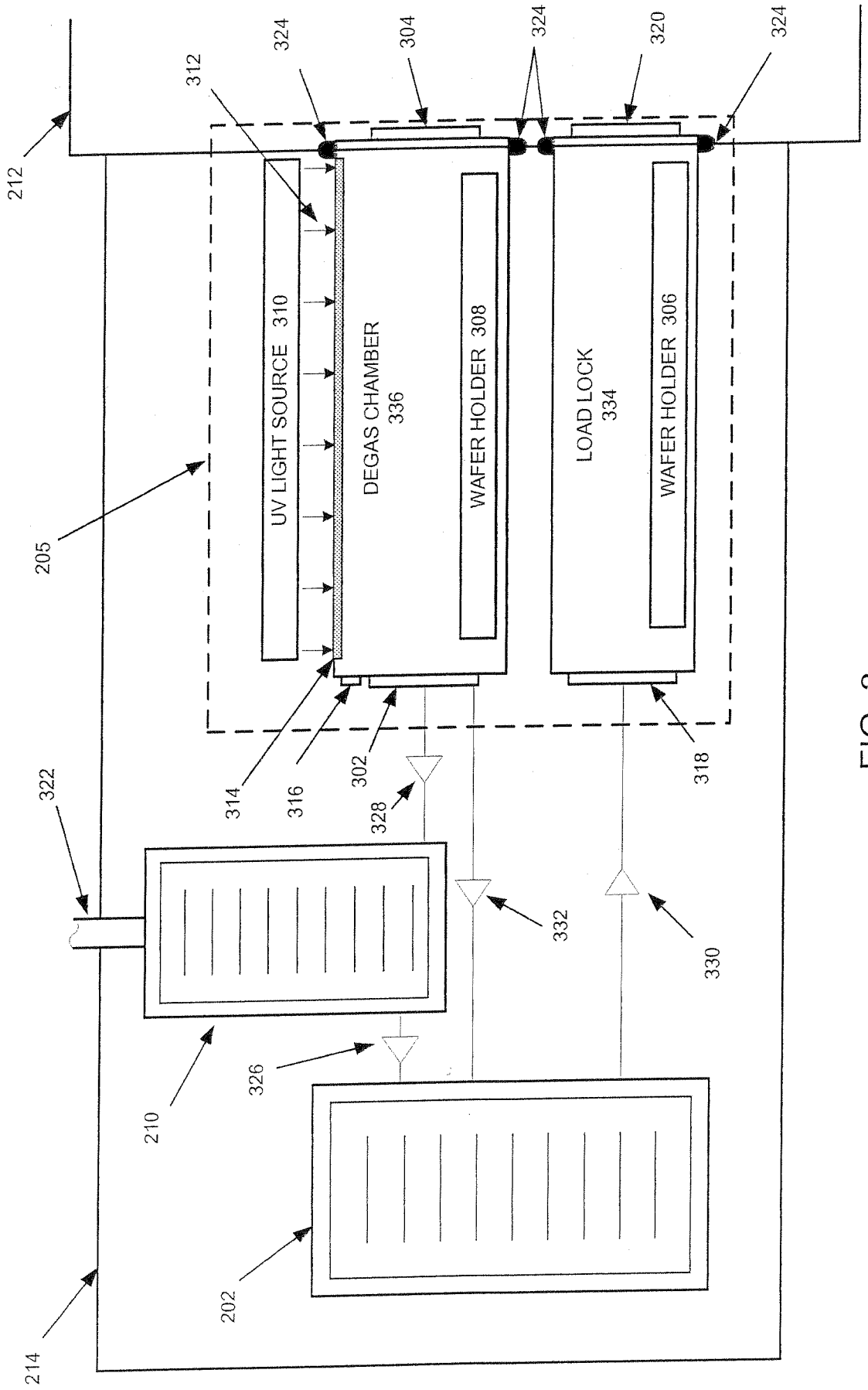

212
312
324
304
324
320
324
UV LIGHT SOURCE 310
DEGAS CHAMBER 336
WAFER HOLDER 308
LOAD LOCK 334
WAFER HOLDER 306
205
314
316
302
328
318
322
332
330
326
210
202
214

FIG. 3

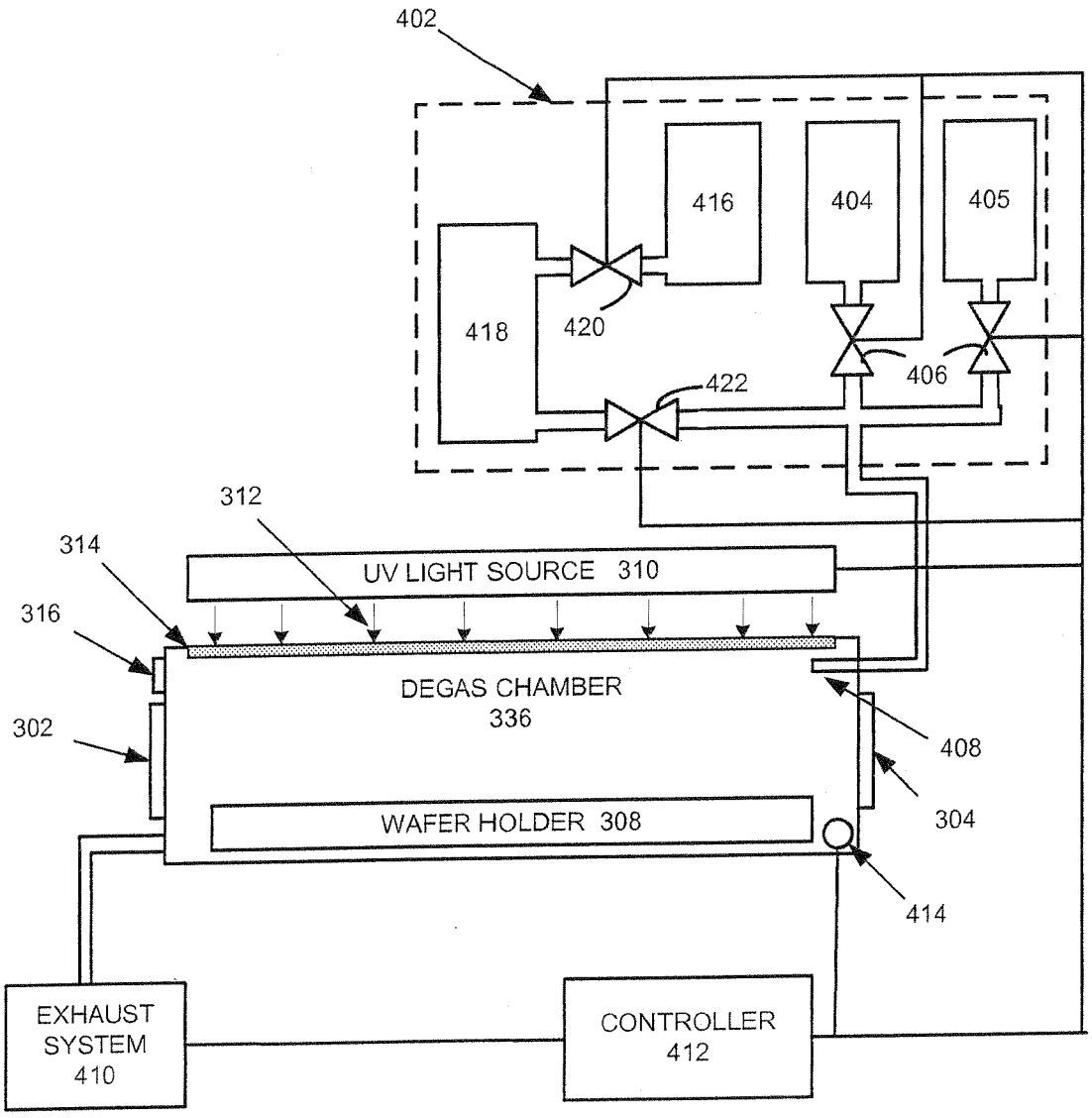

402
416
404
405
418
420
406
422
312
314
UV LIGHT SOURCE 310
316
DEGAS CHAMBER
336
302
408
304
WAFER HOLDER 308
414
EXHAUST
SYSTEM
410
CONTROLLER
412

FIG. 4

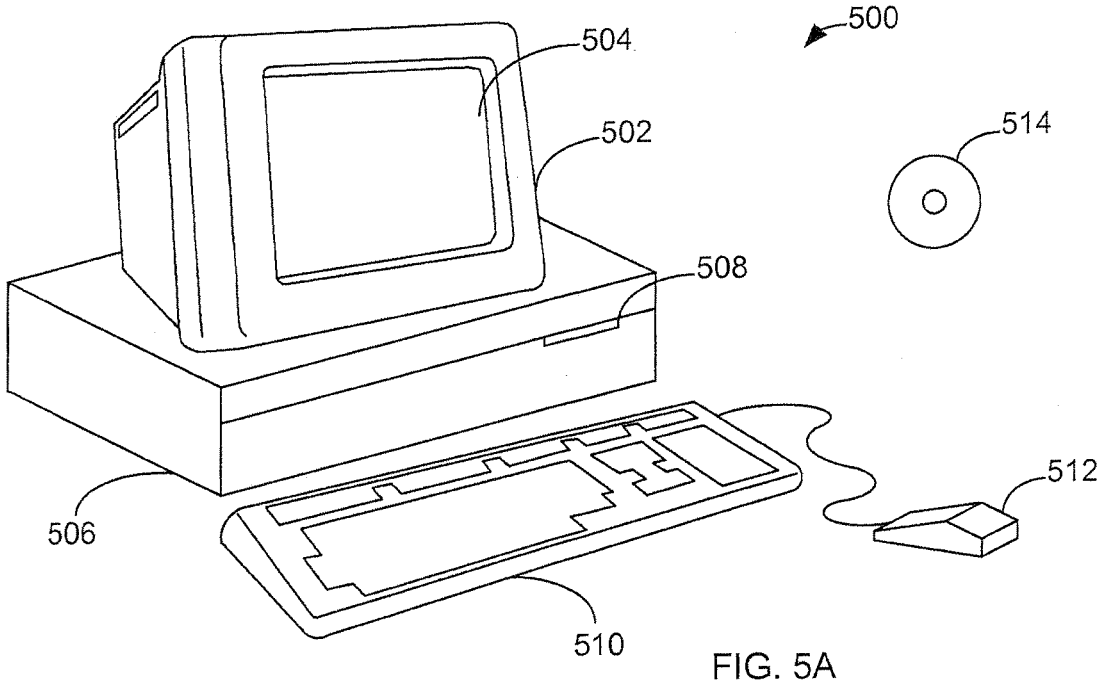

500
504
502
514
508
512
506
510

FIG. 5A

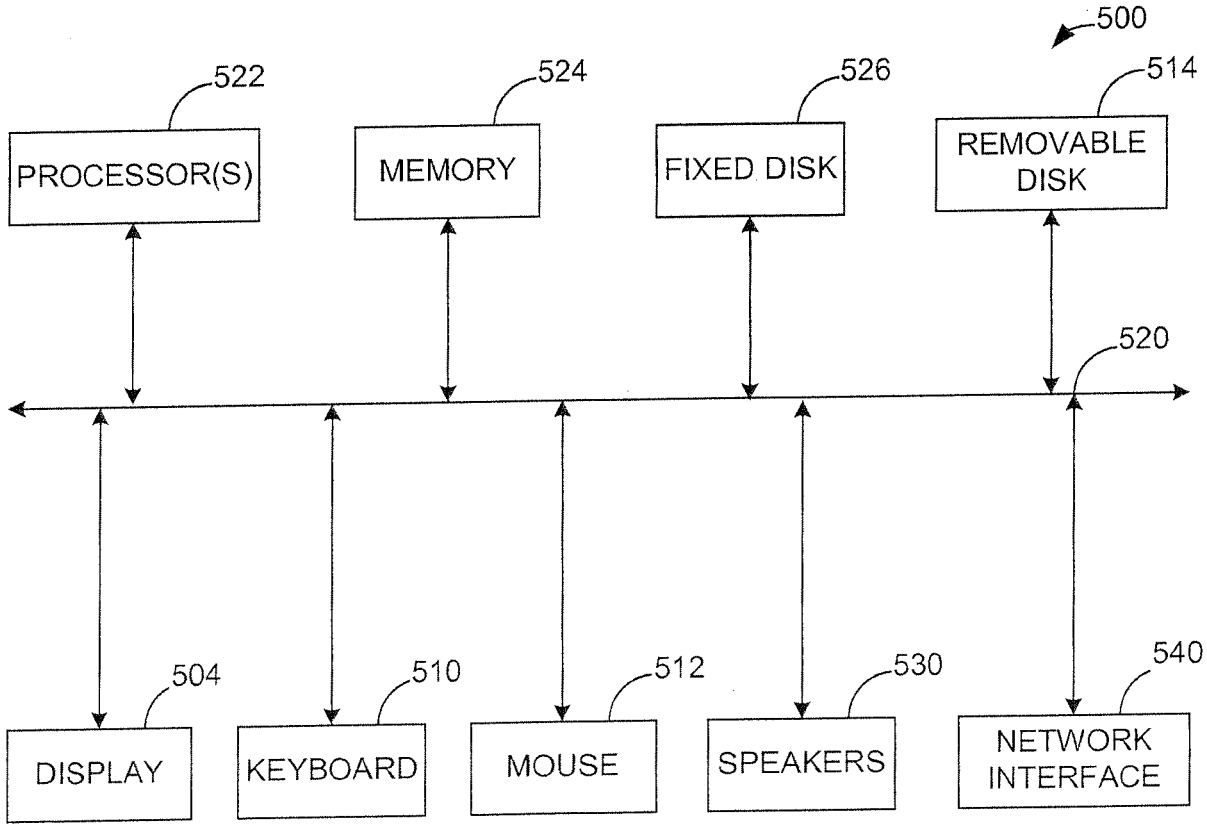

500
522
524
526
514
PROCESSOR(S)
MEMORY
FIXED DISK
REMOVABLE DISK
520
504
510
512
530
540
DISPLAY
KEYBOARD
MOUSE
SPEAKERS
NETWORK INTERFACE

FIG. 5B

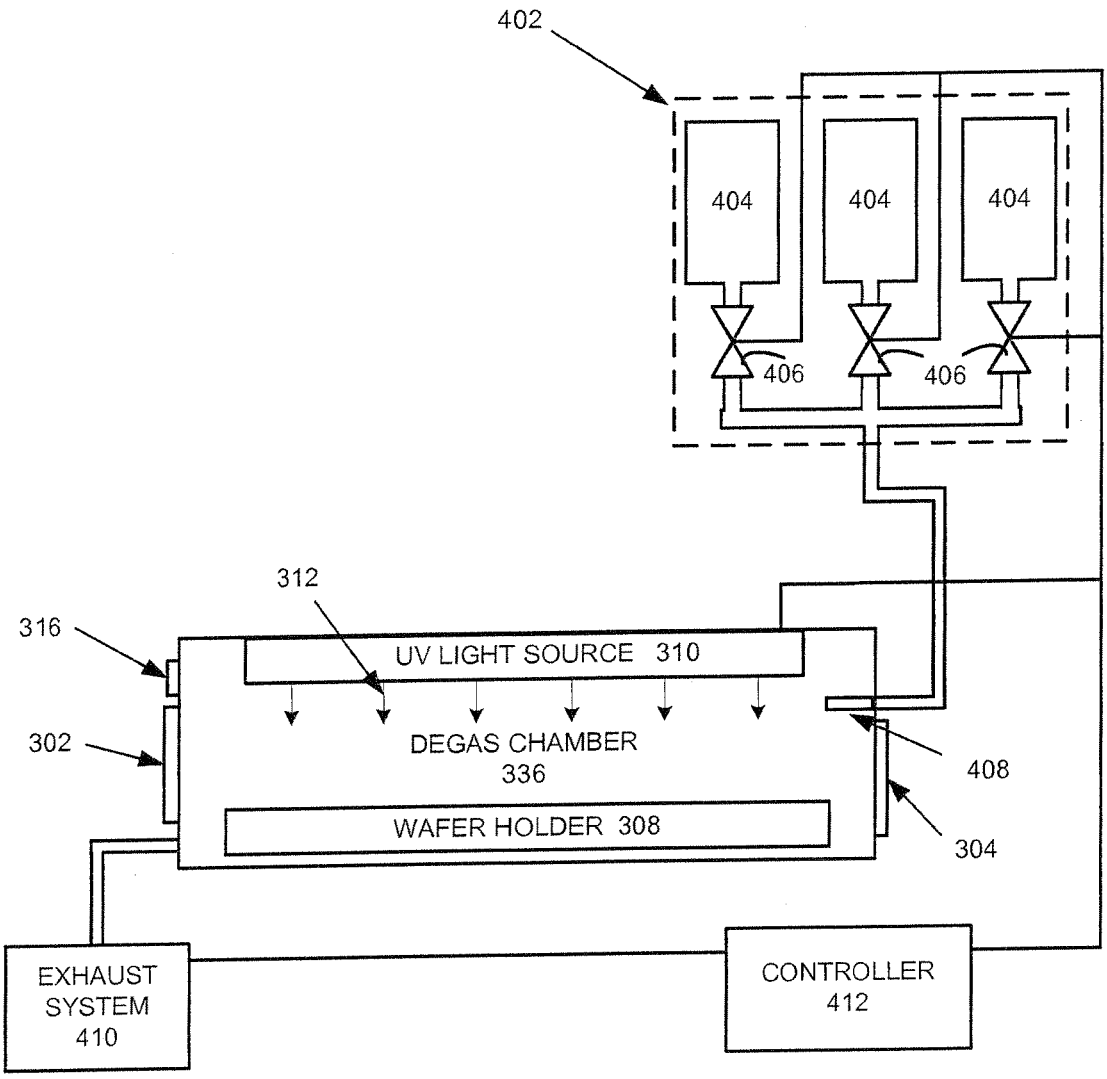

402
404
404
404
406
406
312
316
UV LIGHT SOURCE 310
302
DEGAS CHAMBER
336
408
WAFER HOLDER 308
304
EXHAUST
SYSTEM
410
CONTROLLER
412

FIG. 6

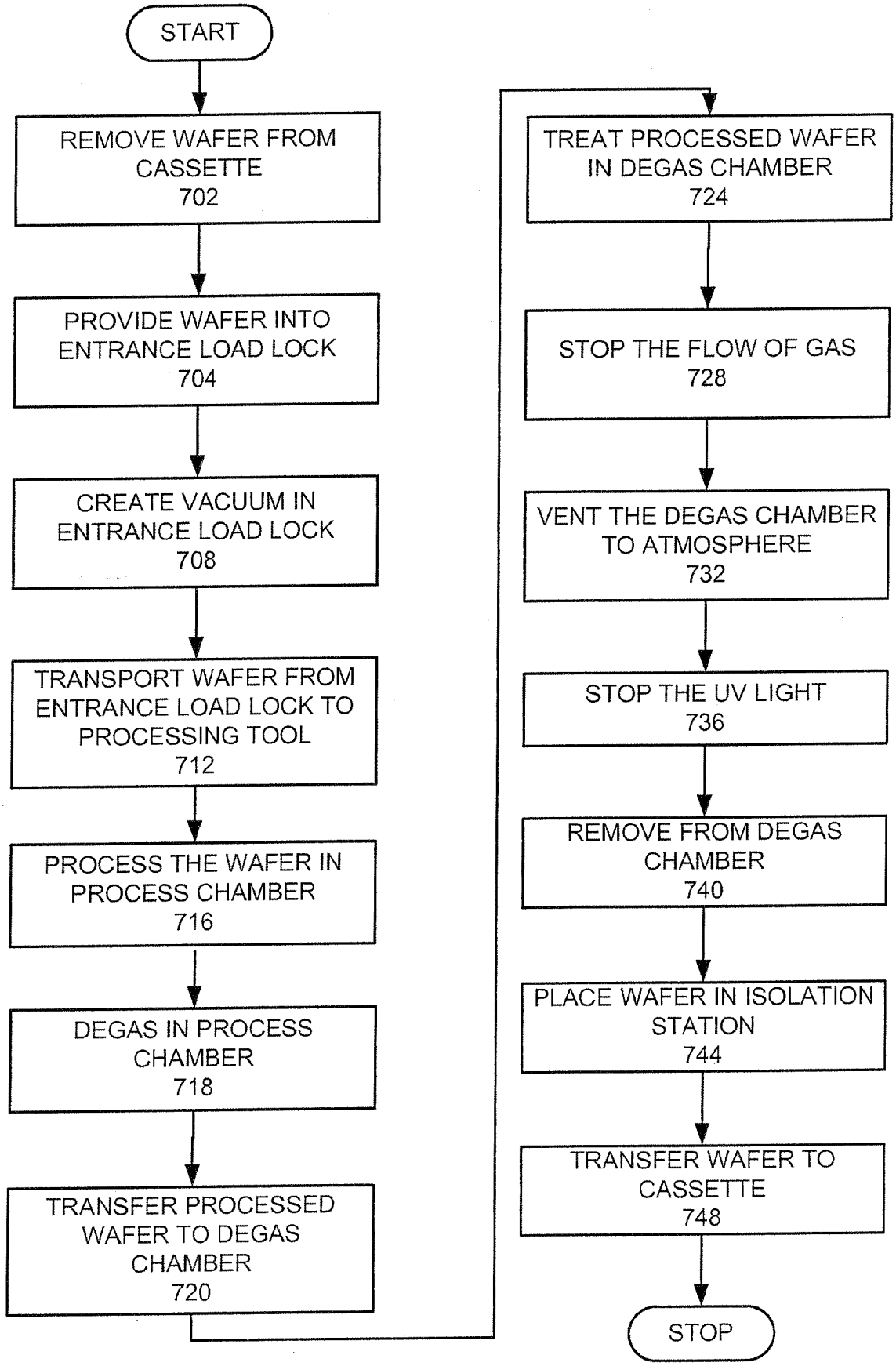

START
REMOVE WAFER FROM CASSETTE 702
PROVIDE WAFER INTO ENTRANCE LOAD LOCK 704
CREATE VACUUM IN ENTRANCE LOAD LOCK 708
TRANSPORT WAFER FROM ENTRANCE LOAD LOCK TO PROCESSING TOOL 712
PROCESS THE WAFER IN PROCESS CHAMBER 716
DEGAS IN PROCESS CHAMBER 718
TRANSFER PROCESSED WAFER TO DEGAS CHAMBER 720
TREAT PROCESSED WAFER IN DEGAS CHAMBER 724
STOP THE FLOW OF GAS 728
VENT THE DEGAS CHAMBER TO ATMOSPHERE 732
STOP THE UV LIGHT 736
REMOVE FROM DEGAS CHAMBER 740
PLACE WAFER IN ISOLATION STATION 744
TRANSFER WAFER TO CASSETTE 748
STOP

FIG. 7

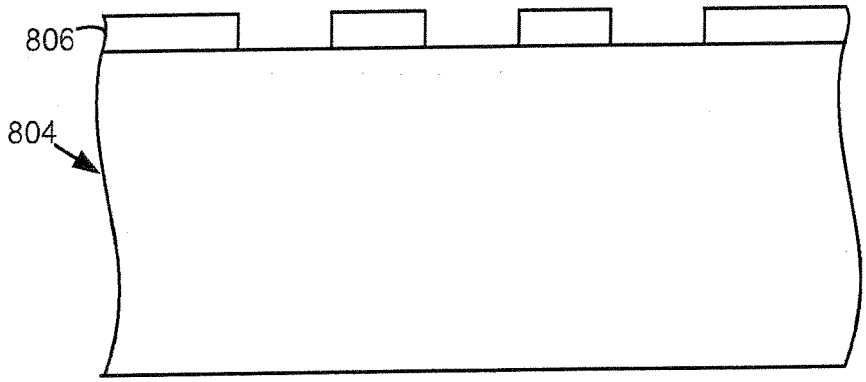


FIG. 8A

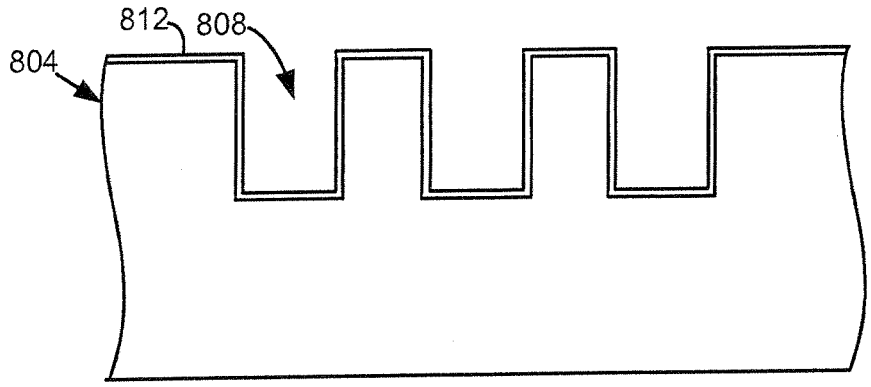


FIG. 8B

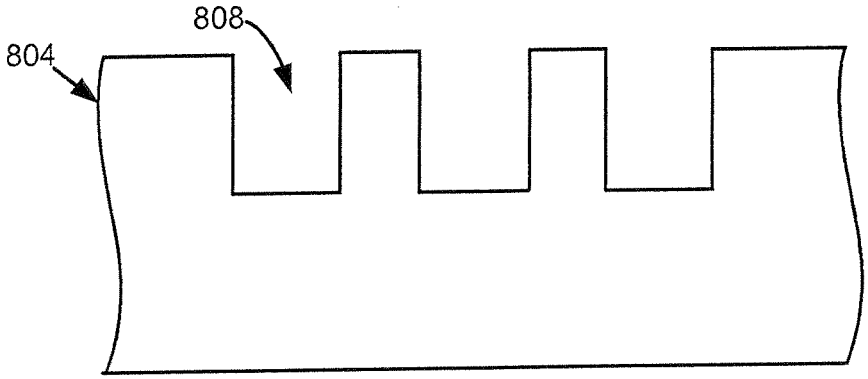


FIG. 8C

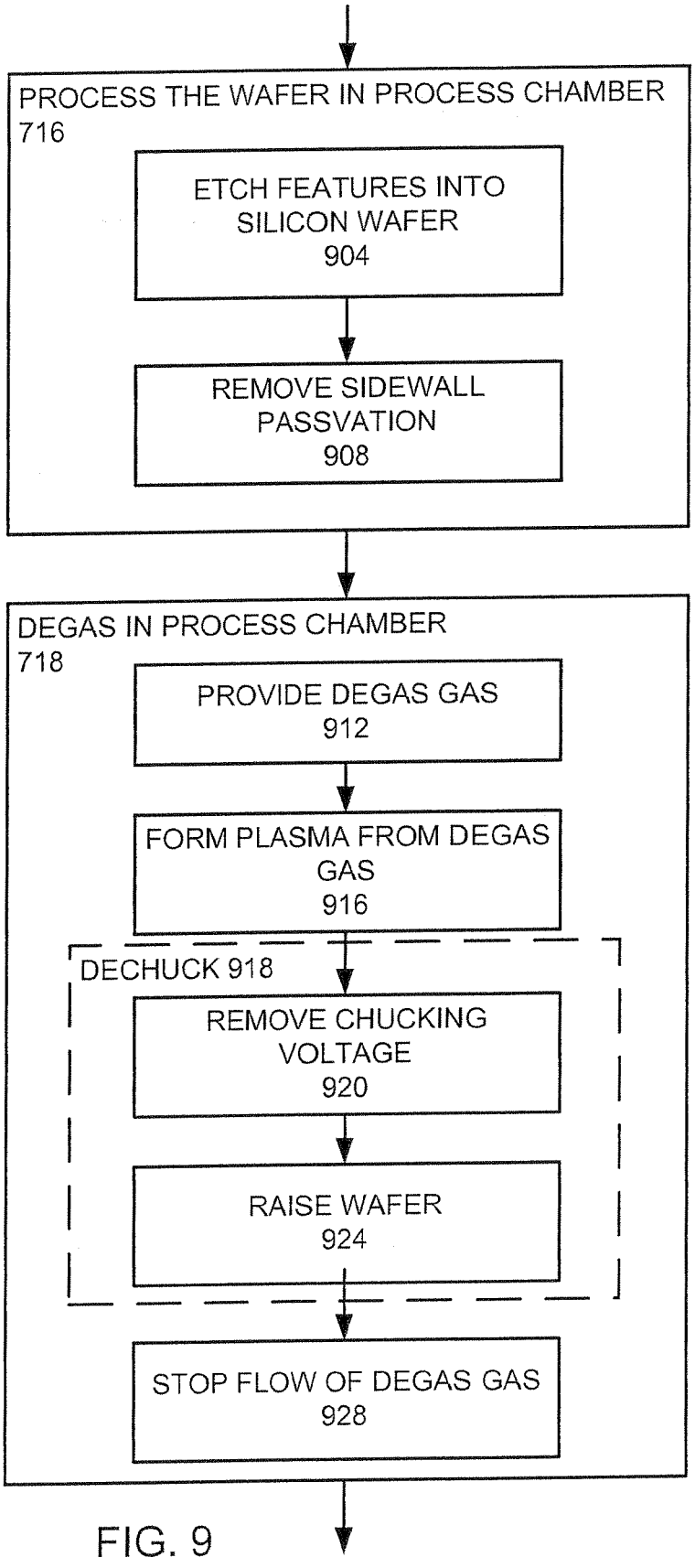

PROCESS THE WAFER IN PROCESS CHAMBER
716
ETCH FEATURES INTO SILICON WAFER
904
REMOVE SIDEWALL PASSVATION
908
DEGAS IN PROCESS CHAMBER
718
PROVIDE DEGAS GAS
912
FORM PLASMA FROM DEGAS GAS
916
DECHUCK 918
REMOVE CHUCKING VOLTAGE
920
RAISE WAFER
924
STOP FLOW OF DEGAS GAS
928

FIG. 9